

2022 OCP GLOBAL SUMMIT Experience Center

Once again, our expo hall will include the OCP Summit Experience Center. Added in 2019, this has become an extremely popular attraction in the Exhibit Hall where engineers showcase best-in-class product demos, solution stacks, software and hardware tools, and technologies under development or recently released by the various OCP Projects.

This area gives the OCP Community a venue to showcase OCP-recognized product offerings, discuss Community-authored specifications and emerging technology in the pipeline, while receiving direct feedback from Summit attendees. This is hands-on, engineering lab experience.

The OCP Summit Experience Center will have stations arranged as small labs and resourced with engineers involved in the OCP Projects. See below for a list of this year's stations.

1. OCP Hardware Management Modules - scalability, flexibility, sustainability.
 - Participating Companies: Intel Corporation, Gowin Semi, Lattice Semi, Inspur
 - DC-SCM
 - Gowin: Implementing DC-SCM 2.0 LTPI- RoT and TPM functions in modern FPGAs
 - Inspur: Integrating DC-SCM to support PFR and TPM on management board
 - Intel: LTPI v1.0 compliant implementation live demo running on Intel's DC-SCM 2.0 modules.
 - Lattice Semi: Enhancing DC-SCM LTPI with Security and Control integrated
 - RunBMC
 - Intel: In this Demo Intel will present fully featured OpenBMC FW running on Intel CycloneV FPGA SoC RunBMC module.
2. Networking - 700Tb DDC Solution
 - Participating Companies: Credo Semiconductor, DriveNets, UFIspace
 - Display of the DDC evolution from 2020 (AT&T initial proposal) through to 2022 this includes:
 - 96Tb Jericho2 / Ramon Cluster spread across three racks as AT&T showing seismic rated racks with 400Gb fabric

- 350Tb Jericho2C+ / Ramon Cluster spread across 3 racks using standard 4 post racks with 400Gb fabric
 - 700Tb Cluster spread across 4 racks with 1.6Tb OSFP-XD fabric
 - The power efficiency of these DDCs have improved by 3x in just 3 years and the density has improved by 7x!
 - Open box display of NCP and NCF systems
 - DriveNets hosting a live demonstration of their cluster operation
- 3. Open System Firmware (OSF)
 - Participating Companies: Ampere Computing, Wiyynn, Meta, Supermicro
 - Ampere Computing: TianoCore/EDK2, LinuxBoot, and OpenBMC running on Ampere's Cloud native platform.
 - Supermicro: Supermicro server based on Intel SapphireRapids Scalable Processor, booting with Open System Server (FSP/coreboot/LinuxBoot).
 - Wiyynn and Meta: Wiyynn single socket server based on Intel SapphireRapids Scalable Processor, booting with Open System Server (FSP/coreboot/LinuxBoot).
- 4. Time Appliance Project (TAP)
 - Participating Companies: Meta, Intel, Broadcom, nVidia, Calnex, ADVA, Timebeat.app, SiTime
 - Showcase of various time domain solutions under development, including a Dual GNSS Time Card, time cards from ADVA, Intel, nVidia, Celestica and a Broadcom Time Aware Switch and Calnex Time Testing Solutions
 - Showcase PTM on the Intel NUC in collaboration with AMI.
 - Showcase Broadcom's Time Card
- 5. P4 Integrated Network Stack (PINS)
 - Participating Companies: Open Networking Foundation (ONF), Intel, Google
 - WCMP using SD Fabric - PINS demo video
 - SAI Generic Programmable Extensions - video
 - Edgecore Wedge 100 switch - static demo
- 6. OCP Network Interface Card (NIC) R3.0
 - Participating Companies: Amphenol, Broadcom, Meta, TE Connectivity
 - Amphenol: Connector Demo Board
 - Broadcom: Single Host & Multi Host NICs & Servers
 - Meta: Next-gen server with Tall Small Form Factor (TSFF) NICs
 - TE Connectivity: Cable & Connector Demo